#### а

absorbed photons 69-72, 76, 143, 144 accelerator vacuum chambers 175, 265 amount of ideal gas 217 effective pumping speed 227 gas close volume 216-218 gas density and pressure 216–217 gas density evolution, equations for 422 - 425gas dynamics modelling 265 gas flow rate 217, 218, 220 materials for aluminium alloys 83-84 ceramics 85-86 copper and copper alloys 84-85 elastomer 87 glass 82, 85-87 stainless steel 82-83 titanium and titanium alloys 85 molar and molecular mass, of common gases 219 NEG coating to 188 operating requirements 81-82 pumping characteristics 221-222 purpose of 81 surface treatments air bake 106 bakeout method 105-106 cleaning procedure 102–105 surface coatings 108-109 vacuum firing 106–107 thermal outgassing 87-101 total and partial pressure 218 vacuum conductance of long tubes 224–225

in molecular flow regime 223 orifice 224 series and parallel connection of tubes 226 of short tubes 225-226 vacuum system with pump 223 velocity of gas molecules 218-219 accelerator vacuum system design 25, 62, 142, 215, 246, 265 activated charcoal 281, 324, 333-336, 338, 340-343 adsorption equilibrium 88–90 adsorption isotherm 89–91, 270, 272, 273, 275, 276, 279, 282-284, 286, 324, 331, 332, 334, 335, 337 alumina 83, 85, 86, 96, 375 aluminium based absorbers 338-340 amorphous carbon coating 337-338, 369 angular flux 32, 34, 50 antechambers 18-20, 69, 153-155, 175, 176, 181, 186, 187, 208, 227, 230, 232, 233, 240, 251, 252, 357, 359, 361, 363, 365, 408, 445

# b

beam chamber size lower limit 17 beam chamber size upper limit 17 beam conditioning 131, 149, 205, 208, 371, 380, 384, 403 beam–gas interaction background noise in detectors 8 beam particle loss 8 Bremsstrahlung radiation 10 lifetime 8

Vacuum in Particle Accelerators: Modelling, Design and Operation of Beam Vacuum Systems, First Edition. Oleg B. Malyshev. © 2020 Wiley-VCH Verlag GmbH & Co. KGaA. Published 2020 by Wiley-VCH Verlag GmbH & Co. KGaA. beam-gas interaction (contd.) particle accelerators associated with radiation damage of instruments 10 - 11residual gas ionisation 9 risk to personnel safety 11 sensitive surface, contamination of 9 - 10beam-induced electron multipacting (BIEM) effects on vacuum 376 electron cloud build-up, in LHC beam pipe 350 electron sources 356 negative impacts 350 observation in CERN Large Hadron Collider (LHC) 380, 381 observation tools 386 synchrotrons 408, 409 vacuum chamber wall properties 382 - 386vacuum pressure 381–382 vacuum stability 405–408 beam-induced pressure instability 471 beam lattice 14–15, 19, 25 beam scrubbing 131, 140, 151, 481, 489, 496, 497 beam vacuum system design beam lattice 14-15 check list for 14 data extrapolations 23 distributed pumping layout 19–20 experimental data interpretation 23 experimental errors 23 gas dynamics model 24 limiting factors 17–18 lumped pumping layout 19 magnet design 17 mechanical engineering 17 number and size of pumps 20 required mechanical aperture 15 - 16sources of residual gas 20 thermal outgassing 20 total outgassing rate 20, 21

vacuum chamber cross sections 18–19 vacuum modelling and design considerations 21, 22 Boyle–Mariotte law 217 Bremsstrahlung radiation 8, 10, 11, 208, 279, 357 Brunauer, Emmett, Teller (BET) equation 275, 276 isotherm 90, 275, 276 bunched-beam heavy ion accelerators 472, 473 dynamic vacuum processes of 473

### С

carbon based adsorbers 333-337 carbon fibre material 334, 335 charged particle accelerators 1, 2, 7, 29, 269 chemisorption 273, 274 Clausius-Clapeyron law 93, 286, 288 COLDEX beam screen calorimetric system 396 BS with saw-tooth, PSD of 326-328 Cu beam screen, PSD for 324 experimental facility 321-324 secondary PSD yields 325-326 temperature oscillations 329-331 vacuum transient effect 328 conductance-limited pumping 228, 242, 475, 478 copper based absorbers 340-341 critical current 421, 433 beam-gas ionisation cross sections 465 for cryogenic vacuum chamber 426 - 427for infinity long vacuum chamber 427 - 428ion impact energy 465 ion-stimulated desorption yields 465-466 pumping speed 466 for short vacuum chamber 431-434 total error in 466

cryogenic vacuum chambers adsorption isotherms 273-279 cryosorbers 331-341 cryotrapping 279-281 desorbed gas, temperature of 318-321 equilibrium pressure 273 hydrogen gas 276 operating temperature, selection of 286 - 289photon induced molecular cracking, of cryosorbed gas 312-318 photon-stimulated desorption process discovery of secondary 301-306 experimental facility for 301 initial considerations 300 primary PSD yields 308-310 PSD yields calculation 306-308 secondary PSD yields 310-312 physisorption 281-282 pressure and gas density 269-272 synchrotron radiation 289 infinitely long vacuum chamber 291 - 294short vacuum chamber 294-300 types 290 cryosorbers for beam screen aluminium based 338-340 amorphous carbon coating 337-338 carbon activated charcoal 333-334 carbon fibre material 334, 335 considerations 341 copper 340-341 criteria for 333 distributed 342 laser ablation surface engineering 341cryosorption 273, 298, 331, 338, 341, 343 cryotrapping 279-281 d

Dalton law 218 desorption yield measurements 481–482 Diamond Light Source (DLS) 11, 24, 232, 258–259 differential pumping, vacuum system with 265, 266 DR equation 276 DRK equation 276, 278, 284 dynamic pressure and beam lifetime calculations 476–479 dynamic vacuum instabilities, mitigation of 504–505

#### е

effective pumping speed 88, 98, 109-111, 156, 226-228, 251, 258-260, 296, 301, 328, 407, 425, 426, 476, 482, 486, 487 elastic recoil detection analysis (ERDA) 195, 483 electron cloud (E-cloud) build-up in LHC beam pipe 350 electron sources 356 models 351-356 observation in CERN Large Hadron Collider 379 observation tools 386-390 problem 349 synchrotrons 408, 409 vacuum chamber wall properties 382-386 vacuum effects 376 vacuum pressure 381-382 electron energy estimation 376 electron stimulated desorption (ESD) bakeout effect 122-123 copper surface preparation 125 definition 109, 110 for different materials as function of dose 112–113 estimation 378 as function of amount of desorbed gas 113-114 as function of electron energy 119 - 122measurements 109–111 vs photon stimulated desorption 144pumping duration effect 114–119

electron stimulated desorption (ESD) (*contd.*) surface polishing 123–125 surface treatment 125 vacuum chamber temperature 125–128, 142 vacuum firing 125 electronic stopping 495, 499, 500 equivalent free path, of gas molecules 220

# f

fast ion instability 9, 14 forward scattering photon reflectivity 64, 66, 71 Freundlich equation 274, 276–278

# g

Ga-As photocathode lifetime 9 gas close volume 216-218 gas dynamics model cryogenic vacuum chambers under SR 289-300 infinitely long vacuum chamber 291 - 294short vacuum chamber 294-300 of vacuum system 24-25 gas flow rate 215, 217, 218, 220–223, 231-233, 241, 246, 248, 249, 252, 255 gas injection, into tubular vacuum chamber 241 getters 108, 109, 176, 177, 179, 188, 193, 195, 230, 466, 472, 475, 492, 493, 505 Glidcop<sup>®</sup> 85, 112 grazing incidence 63, 64, 66, 142, 143, 308, 472, 474, 478, 487, 489-491,

# h

He and  $H_2$  isotherms on Cu plated stainless steel 278 heavy ion-induced desorption 480 angle dependence 495–496 CERN set-up 486, 487 cleaning methods 493–494

493-496, 504

conditioning methods 496-497 copper 491–492 cryogenic targets 488-489, 497-499 desorption yield measurements 481-482 energy loss scaling 494-495 experimental results 489-499 GSI set-up 486-488 high-melting materials 492 IMP set-up 489 inelastic thermal spike model 500 - 504ions interaction with matter 499-500 materials analysis 483-485 noble getter surface coatings 493 noble metal surface coatings 492-493 stainless steel materials 490 TiZrV-coated sample tubes 491 TSL set-up 488 Henry's law 273, 274 He pressure wave measurements 280 H<sub>2</sub> isotherms on bare surface 283 H<sub>2</sub> isotherms on Cu plated stainless steel 276–278, 283, 285, 286 H<sub>2</sub> isotherms on electro-polished stainless steel 286 H<sub>2</sub> isotherms on stainless steel 285  $H_2$  isotherms, temperature dependence of 283 hydrogen adsorption isotherms 270, 272, 286, 331, 332

# i

ideal volumetric pumping speed 222 impingement rates 221, 248, 260–263 incident electron flux estimation 376–377 inelastic thermal spike model 500–504 infinitely long vacuum chambers 425 critical current 444–445 gas density critical current 426, 427 cryogenic vacuum chamber 426–427 quasi-static case 427

room temperature vacuum chamber 425-426 stability criteria 428 vacuum chamber with beam screen 426 vacuum chamber with pumping slots 425 vacuum chamber without beam screen 426 vacuum chamber without pumping slots 425 ion stimulated desorption on gas density 441-443 synchrotron radiation 291 with holes in beam screen 292 - 294without beam screen 292 two-gas system 443 insulating materials 364, 374–376 intersecting storage ring (ISR) vacuum system, 471 ion desorption stability 421, 465 ion energy in vacuum chamber dipole magnetic field 461 quadrupole magnetic field 461-462 solenoid magnetic field 462-464 without magnetic field circular beams 455-458 flat beams 458-460 ion-induced desorption 421, 423–426, 428, 441, 449, 453-455, 472-474, 480-504 ion induced pressure instability infinitely long vacuum chamber 425 - 428multi-gas system 437-438 short vacuum chamber 428-437 two-gas system 438-440 VASCO code 447-455 ion stimulated desorption (ISD) 155 bakeout effect and argon discharge cleaning 161 for condensed gases 163 for different materials 160 vs. electron stimulated desorption 161 function of ion dose 156-158

function of ion energy 158 function of ion mass 159–160 function of temperature 161–163 on gas density infinitely long vacuum chambers 441 single gas estimation 446 two gases system 443, 446 vacuum chambers with given pumping speed 441–442 ion trapping instability 9, 14

### k

Knudsen number 220 Kovar<sup>®</sup> 86

### I

Langmuir isotherm 89, 90, 274, 276 Large Hadron Collider (LHC) BIEM and E-cloud observations 379–405 cryogenic vacuum system 401–405 laser ablation surface engineering (LASE) 341, 360 Lorentz equation 32

#### m

M-branch 488 metallisation brazing 85 molecular beaming effect GaAs photocathode electron gun 262–264 heavy ion stimulated induced desorption 264 Molflow+ 58, 59, 245, 246 Monte Carlo methods 2, 154, 190, 245

### n

non-evaporable getter (NEG) coated vacuum chambers 20, 176 ASTeC activation procedure 185 beam path 187 CERN–BINP activation procedure 183–184 manufacturing cost 176 nature of getter materials 176 NEG coatings 177–179

non-evaporable getter (NEG) coated vacuum chambers (*contd*.) operation conditions 176 synchrotron radiation 196–199 ultimate pressures in 195–196 use of 208-209 non-evaporable getter (NEG) coatings activation temperature 178 activation procedure 182-188 benefits 207-208 classification of sorption pumps 177 cylindrical magnetron deposition configuration 180 electron stimulated desorption yield 204 film characterisation 181–182 gas diffusion barrier 178 high pumping speed 178 lifetime 193–195 at low temperature 207 magnetron sputtering 179 planar magnetron deposition 179, 180 primary and secondary electron yields 204 - 206pumping optimisation at ASTeC 190 pumping optimisation at CERN 188 pure metal alloy 178 reducing particle/electron stimulated desorption from 200 sticking probabilities 200 surface resistance 206-207 Ti–Zr–V films 189, 190 vacuum chamber cross sections 186, 187 non-evaporable getter (NEG) pumps 177

#### 0

one-dimensional gas diffusion model 228 accelerator vacuum chamber section 231–232 advantage 231 closed loop boundary conditions 233, 235, 237

continuous flow fluid dynamics 229 gas balance 229 gas injection, into tubular vacuum chamber 241 global and local coordinates 238 - 240molecular beaming effect 259–264 open end boundary conditions 233, 237 and TPMC model 257, 258 uncertainties 240 vacuum chambers with known pressures 244-245 with known pumping speeds at the ends 241-244 OrAnge SYnchrotron Suite (OASYS) 56 OSCARS 59 oxide dispersion strengthened (ODS) copper 85 oxygen-free high conductivity copper 84, 491, 492

# р

particle accelerators associated with beam gas-interaction background noise detectors 8 beam particle loss 8 Bremsstrahlung radiation 10 radiation damage of instruments 10 - 11residual gas ionisation 9 risk to personnel safety 11 sensitive surface, contamination of 9 - 10synchrotron radiation 29 vacuum design objectives 12 vacuum specifications 6-13 photoelectron energy distribution curves of Cu co-laminated on stainless steel 74 of gold 72, 73 modification 75 photoelectron production incidence angle effect 76

photon energy effect 72-75 total photoelectron yield 69-72 photon induced molecular cracking, of cryosorbed gas 312-318 photon reflectivity 61, 64 copper mirror 62, 63 diffuse and forward scattered reflectivity 64 experimental set-up 64, 65 flat and sawtooth copper surface 67. 68 flat LHC copper surface 69 photon stimulated desorption (PSD) 128 bakeout effect 137-140 critical photon energy 136–137 for different materials 131 - 134vs. electron stimulated desorption 144 as function of amount of desorbed gas 135 as function of photon dose 131 gauge method 129 incident angle effect 142–144 in-depth studies of 321 measurements 129, 130 vacuum chamber temperature 141 vield data use distributed and lump SR absorbers 153 - 155lump SR absorber 151–153 scaling the photon dose 145 SR photon flux 148–151 synchrotron radiation from dipole magnets 145–148 physisorption 273 vs. condensation 273 cryotrapping 279-281 on gas condensates 281-282 pressure instabilities, in heavy ion accelerators 472, 480 angle dependence 495-496 CERN set-up 486, 487 cleaning methods 493-494 closed system (vessel) 476-478 conditioning methods 496–497 copper 491-492

cryogenic targets 488, 497 desorption yield measurements 481 - 482dynamic pressure and beam lifetime calculations 476-479 energy loss-scaling 494-495 experimental results 489–499 getter surface coatings 492–493 GSI set-up 486–488 heavy ion-induced desorption 480 high-melting materials 492 IMP set-up 489 inelastic thermal spike model 500 - 504ion-optical simulation 478 ions interaction with matter 499 - 500longitudinal vacuum profile 478 - 479materials analysis 483-485 noble metal surface coatings 492-493 stainless steel materials 490-491 TiZrV-coated sample tubes 491 TSL set-up 488 pressure rise method 481

### r

radiated energy and power density 31–32 Redhead's equation 101 residual gas, in vacuum chambers 79–81 ring accelerator, stable operation of 479 Rutherford back scattering (RBS) spectrometry 483

#### S

secondary electron emission incidence angle 374 insulating materials 374–376 re-diffused electrons 371–374 reflected electrons 371–374 surface material effect 368–369 surface roughness effect 369–371 surface treatment effect 367 secondary electron emission (contd.) true secondary electrons 371-374 secondary electron yield (SEY) as function of incident electron energy 367 incidence angle 374 insulating materials 374 measurement method 365-367 re-diffused electrons 371-374 reflected electrons 371-374 surface material effect 368-369 surface roughness effect 369-371 surface treatment effect 367 true secondary electrons 371-374 short vacuum chambers 428 with gas density at the ends 428-431 with pumping speed at the ends 431-434 synchrotron radiation 294 given pressure at the ends 296 - 298given pumping speed at ends 298-300 two-gas system 439, 440 without beam screens 434-437 spectra 56–59, 73, 74, 100, 101, 388, 389, 437, 492 sputter ion pump (SIP) 18, 20, 175, 177, 230, 466 sputtering 74, 179, 481, 492, 497, 500 sticking coefficient 222, 475 sticking probability of sorbing surface 221, 273, 325, 399 storage rings, good vacuum in 8 StrahlSim code 478, 479 superconducting magnets 11, 17, 269, 279, 282, 300, 320, 321, 331, 390, 472 synchrotron radiation (SR) 128 angular flux 32 charged particle emission, in magnetic field 29-32 from dipoles emission duration and critical energy 33-34

photon flux 34-37 photon power 39-41 from insertion devices 43-55 angular aperture 51–52 K-factor 47 method for estimation absorbed power 54–55 motion of charged particles 43 - 45power collected by simple geometry aperture 54 power distribution in wiggler 52 - 54resonant wavelength 45-46 undulator mode 46–51 wiggler mode 46–51 from quadrupoles 42-43 radiated energy and power density 31 - 32synchrotron radiation-vacuum chamber wall interaction 61 photoelectron production 69-76 photon reflectivity 61-69 Synchrotron Radiation Workshop (SRW) 56 SYNRAD+ 58-59, 246

# t

test particle Monte-Carlo (TPMC) method 245 code input 246-248 code output gas density and pressure 250 gas flow rate 248-249 mass of molecules 251 pump effective capture coefficient 251 temperature effect 251 transmission probability 250-251 vacuum conductance 250-251 input parameters, defined set of 252 - 253molecular beaming effect 259–264 one-dimensional gas diffusion model 257 - 264result accuracy 256-257 vacuum chamber in 246

with variable parameters 253 - 256virtual pumping surfaces 252 thermal desorption 22, 87, 93, 94, 100, 101, 112, 130, 156, 175, 185, 230, 252, 253, 289, 308, 337-339, 376, 407, 423, 424, 447, 449, 473-475, 480, 502 thermal outgassing 87 equilibrium pressure 89-91 measurement methods conductance modulation method 98 gas accumulation method 99-100 thermal desorption spectroscopy 100 - 101throughput method 97–98 two-path method 98-99 during pumping 88 rate of materials 93-97 91 - 93vapour pressure thermal transpiration effect 270-272 titanium sublimation pump (TSP) 20, 177,466 total beam lifetime 8 transmitted photons 144 turbo-molecular pumps (TMP) 20, 83, 186, 265-267, 270, 323, 466

#### u

ultra-high vacuum/extreme high vacuum (UHV/XHV) vacuum system design 175

### V

vacuum definition 5 ranges/degrees of 5 vacuum chamber design active methods 363–365 active *vs.* passive mitigation methods 365

chamber wall properties 382 DA $\Phi$ NE dipole 364 with given pumping speed 441, 442 insulating materials 374-376 KEK 359 observations with beams 394-401 passive mitigation methods 357 pressure variation 381 surface properties at cryogenic temperature 391-394 wiggler 359 vacuum conductance of long tubes 224, 225 in molecular flow regime 223 orifice 224 series and parallel connection of tubes 226 of short tubes 225, 226 Vacuum Plumber's Formulas 223 vacuum specifications 11-12 for particle accelerators 6–13 vacuum system designer 6, 13, 95 VASCO code basic equation 447-448 cylindrical geometry 447 finite elements 447-448 multi-gas model in matrix form 448-451 vs. single gas model 452–455 second order linear differential equation, transformation of 450 - 451set of equations 451-452 time invariant parameters 447

# X

Xe adsorption isotherms 331 xenon adsorption isotherm 332 X-ray Oriented Programs (XOP) 56